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Experimental investigation of dimension effect on electrical oscillation in planar device based on VO₂ thin film

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1. Introduction

Owing to the sharp electrical switching property based on its electric field-induced resistance change, vanadium dioxide (VO₂) thin films have attracted considerable attention for demonstrating the metal-insulator transition theories and its potential in various electrical and optical applications [1-11]. Especially, two-terminal planar junction devices based on VO₂ thin films show strong nonlinear current-voltage (I-V) characteristics [5]. This characteristic was also observed in other materials including perovskite oxides [10], organic materials [11], and gallium arsenide (GaAs) [12]. The oscillatory electrical responses have been observed in a circuit composed of a thin-film-based device and serial standard resistor at very low temperatures. Recently, it was reported that the room-temperature electrical oscillation could be obtained in a planar device based on VO₂ thin film [13–15]. In previous studies, however, the device dimension, i.e., the length (L) and the width (W) of the current channel, was fixed as a square-shaped one like 5×5 or $10 \times 10 \,\mu\text{m}^2$, instead of rectangular-shaped ones [14,15].

In this paper, we experimentally investigate the variation of the electrical oscillation properties including an oscillation current (I_0) and an oscillation frequency (f_0) for planar devices with the variation of the device dimensions. Through the experimental investigation, we observe the modification of the generation window of the electrical

ABSTRACT

In this paper, we report on an experimental analysis of dimension effect on a room-temperature electrical oscillation in a planar device using vanadium dioxide (VO₂) thin film. We investigate the variation of the oscillation current (I_0) and frequency (f_0) due to the variation of the dimension of the VO₂ devices, i.e., the length and width of the current channel of the device. For five different VO₂ devices with different dimensions, I_0 and f_0 are observed at room temperature in a simple circuit composed of a dc voltage source and a standard resistor including one of the VO₂ devices. From the experimental investigation, it is concluded that the peak-to-peak amplitude of I_0 and f_0 decrease with the increase of the length and width of the current channel. This indicates that f_0 depends on not only the external source voltage but also the device dimension.

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oscillation (oscillation window) determined with an external source voltage ($V_{\rm S}$) and an external standard resistor ($R_{\rm E}$) according to the variation of the device dimensions. For the examination of the variation of the oscillation properties ($I_{\rm O}$ and $f_{\rm O}$), the resistance of the serial resistor (potentiometer) was fixed at 3.5 k Ω in order to focus only on the dimension effect by removing resistance change. From the examination, it is concluded that $f_{\rm O}$ can be controlled by not only the applied voltage but also the device dimension.

2. Experimental details

VO₂ thin films were grown on c-plane sapphire (Al₂O₃) substrates by employing a pulsed laser deposition technique [16]. The substrate temperature T_{substrate} was kept constant at 500 °C during the deposition. The base pressure of the chamber was 1.33×10^{-4} Pa. A total gas pressure of 0.67 Pa was maintained in the chamber at an oxygen flow of 50 sccm. After the deposition process, the films grown on the substrate were cooled down to room temperature with the same gas condition. The thickness of the grown films was typically ~100 nm. In order to fabricate planar VO₂ devices, the films were patterned into line shapes with photolithography processes and were etched by an ion-beam assisted milling method. For an Au/Ti electrode layer on the etched VO₂ layer, a metallization process was progressed by using an RF sputtering method and a lift-off technique [17]. For the facilitation of the adhesion, the Ti electrode layer was deposited first below the Au electrode one. The widths of the current channels of the VO₂ devices were designed to be narrower than those of the electrodes to avoid a delayed transition of VO₂ outside the



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Fig. 1. (a) The cross-sectional diagram of the fabricated device and the schematic diagram of an experimental setup for measuring the *I*–V characteristics of the devices. (b) The optical microscope plane-view images of five VO₂ devices (Devices I–V). (c) The *I*–V hysteresis loops of Device I measured. (d) The single-loop circuit was designed with a planar VO₂ device, an external standard resistor (*R*_E), and a dc power supply (*V*_S).

electrodes. The dimensions $(L \times W)$ of the current channels of five different VO₂ devices designated as Devices I, II, III, IV, and V were 5×5 , 5×10 , 5×20 , 10×5 , and $10 \times 10 \,\mu\text{m}^2$, respectively. Fig. 1(a) shows a cross-sectional diagram of the fabricated device and a schematic diagram of an experimental setup for measuring *I*–*V* characteristics of the devices. Fig. 1(b) shows optical microscope plane-view images of five VO₂ devices (Devices I–V). For measuring *I*–*V* characteristics, we used a parameter analyzer (Agilent B1500A) with tungsten probe tips of 5 μ m in diameter. The contact resistance

with the devices was $\leq 5 \Omega$, which was $\leq 0.05\%$ compared with the resistance across the device (R_D) at room temperature. To implement the field-induced oscillation and control f_O , a single-loop circuit was designed with a planar VO₂ device, an external standard resistor (R_E), and a dc voltage source (V_S) as shown in Fig. 1(d). A function generator (Agilent 33120A) and a dc power supply were simultaneously utilized to generate rectangular voltage pulses with adjustable dc offsets. The electrical waveforms from the circuit were recorded by a digital storage oscilloscope (HP 54810A).



Fig. 2. (a)–(e) The oscillation window with respect to five devices (Devices I–V). The lower and upper limits of V_{emg} and V_{dis} where the oscillation can be existed are plotted with red squares and blue squares, respectively. Inset panels show *I–V* hysteresis loops of Devices I–V at $R_E = 0$ k Ω .

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